

[54] **LIGHT-EMITTING DIODE  
SEMICONDUCTOR CHIP WITH LEADS**

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Japan  
[\*\*] Term: **14 Years**  
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[52] U.S. Cl. .... **D13/12; D13/99**  
[58] Field of Search ..... **D13/99; D26/1; 362/800;**  
**313/499, 500, 501, 512; 357/17, 74**

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cell #B425.  
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[57] **CLAIM**

The ornamental design for a light-emitting diode semi-  
conductor chip with leads, substantially as shown and  
described.

**DESCRIPTION**

FIG. 1 is a perspective view of a light-emitting diode  
semiconductor chip with leads showing my new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a side elevational view thereof, as seen from  
the right side of FIG. 1;  
FIG. 4 is a side elevational view thereof, as seen from  
the left side of FIG. 1;  
FIG. 5 is a top plan view thereof; and  
FIG. 6 is a bottom plan view thereof.

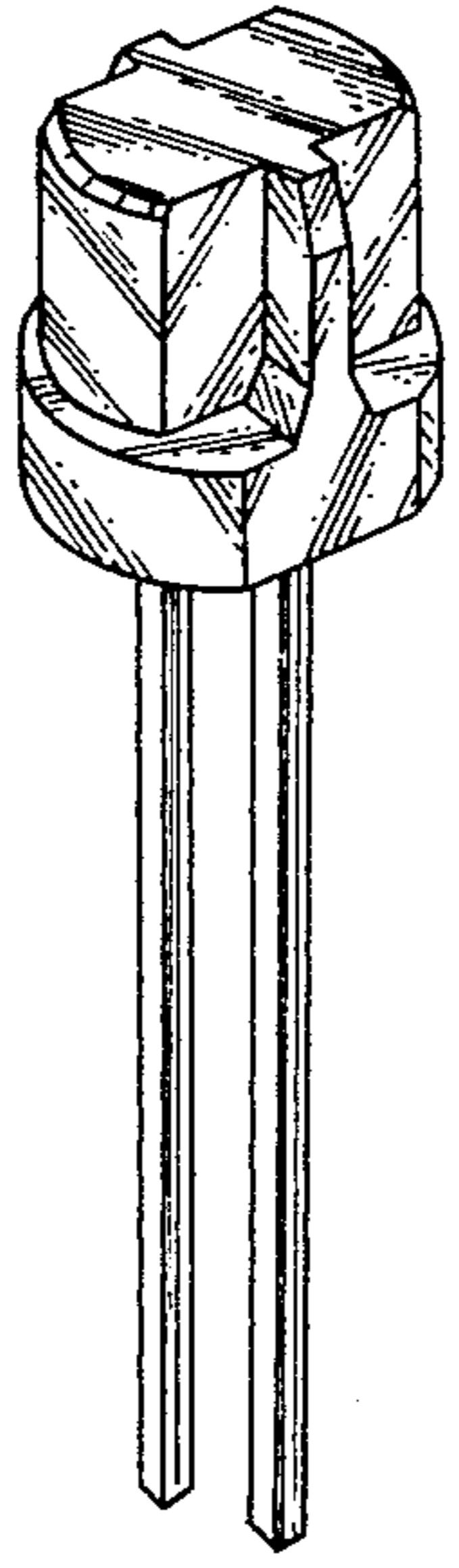


Fig. 5

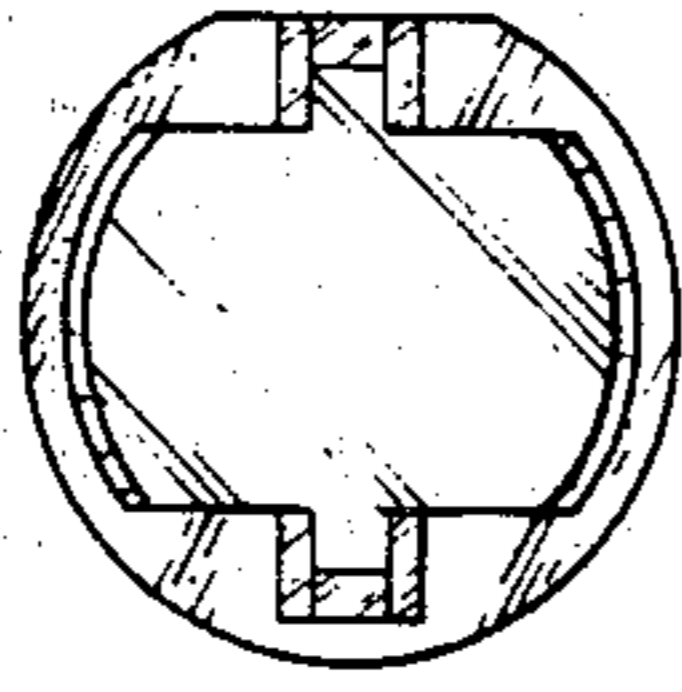


Fig. 6

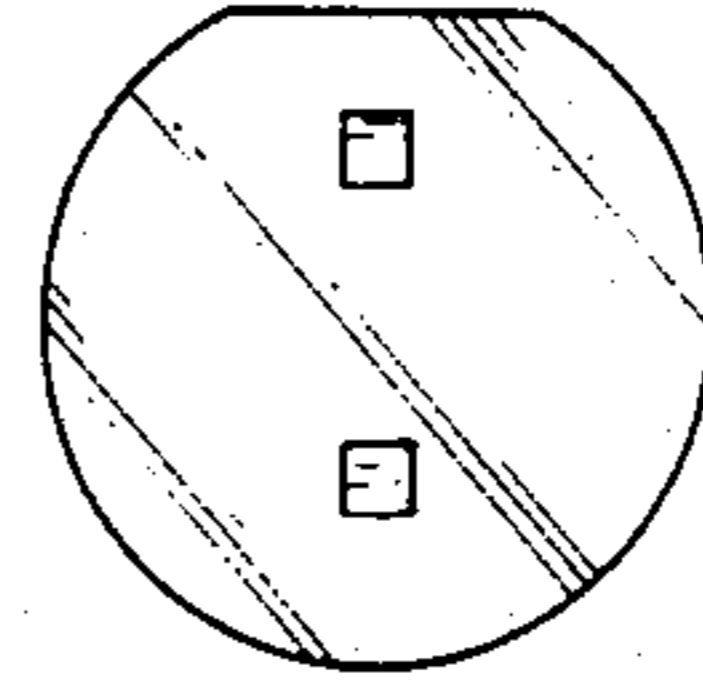


Fig. 4

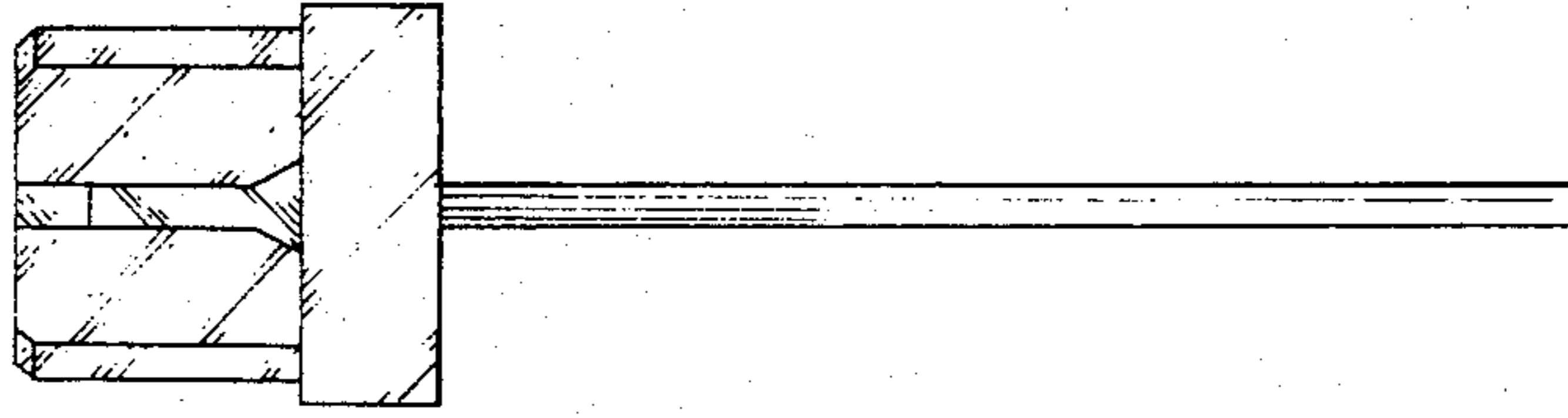


Fig. 3

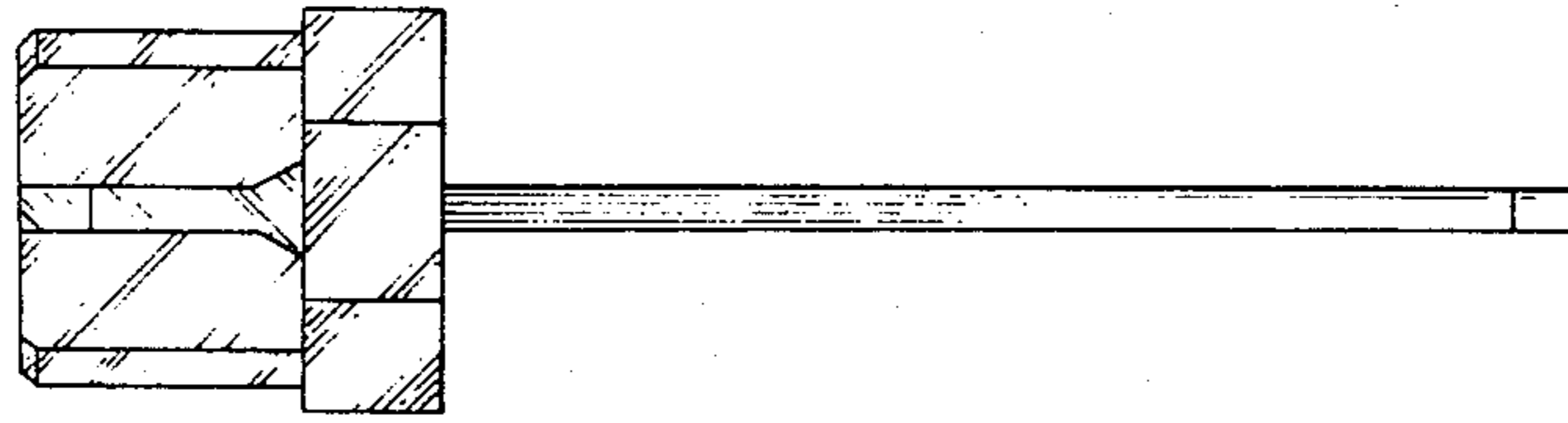


Fig. 2

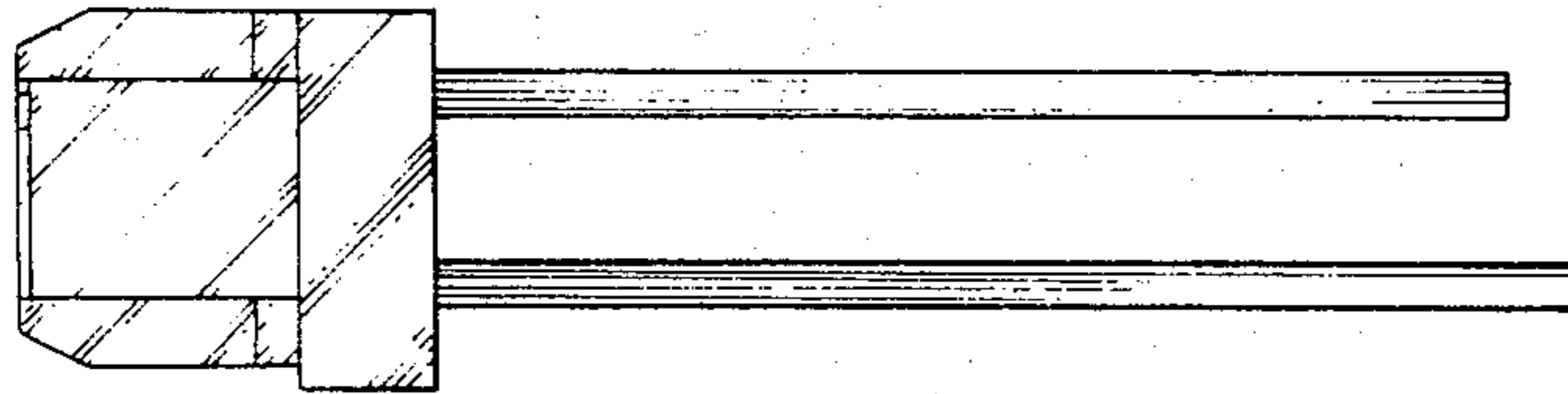


Fig. 1

